

# 4 Prel Amends  
6-13-01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

MAEDA et al

Serial No.:

Filed: March 15, 2001

For: FILM-FORMING SURFACE REFORMING METHOD AND  
SEMICONDUCTOR DEVICE MANUFACTURING METHOD

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Please amend the captioned application as follows:

IN THE CLAIMS:

Please rewrite claims 12 as follows:

12. (Amended) A semiconductor device manufacturing method according to claim 6, wherein the insulating film is a silicon-containing insulating film which is formed by a thermal chemical vapor deposition employing a reaction gas that contains an ozone-containing gas and a tetraethylorthosilicate.